

Thick Film Chip Resistors  
Type MCR Series

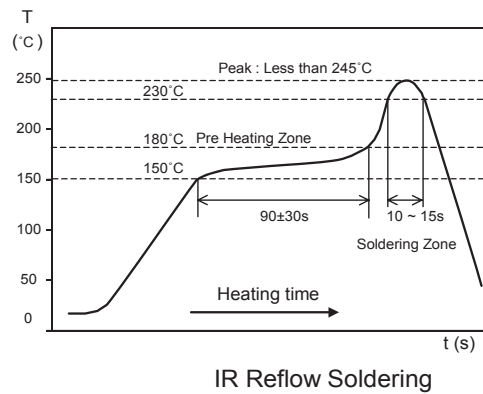
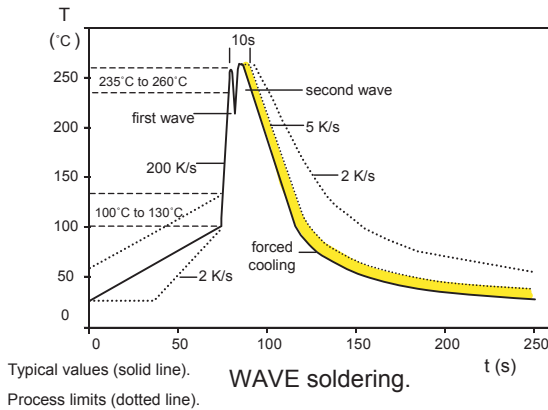
△ Features

- Small size and lightweight with size range per int'l standard.
- Highly stable in auto-placement surface mounting application.
- Compatible with flow and reflow soldering.
- Suitable for lead free soldering.

△ Applications

- Consumer electronics
- Medical equipment
- Telecom equipment
- Automotive, industry
- Computer

△ Soldering Temperature Curve



△ How to Order

Part Number

Example	MCR 0603	T	J	123	LF	
	Type	Size	Packing	Tolerance	Resistance Value	
	MCR	0201	T: Tape	B: ±0.1%	123 = $12 \times 10^3$	LF = Lead Free
		0402		C: ±0.25%	= 12k Ω	
		0603		D: ±0.5%		
		0805		F: ±1%		
		1206		G: ±2%		
		1210		J: ±5%		
		2010				
		2512				

△ Resistance Marking

E-24 Series



3 digit marking for E24  
ex. 473:  $47 \times 10^3 = 47K\Omega$   
105:  $10 \times 10^5 = 1M\Omega$   
1R5:  $15 \times 10^{-1} = 1.5\Omega$   
0:  $0\Omega$



4 digit marking for E241:  $\Omega \sim 10m\Omega$   
ex. 1R00:  $1\Omega$   
R470  $470m\Omega$   
R010  $10m\Omega$

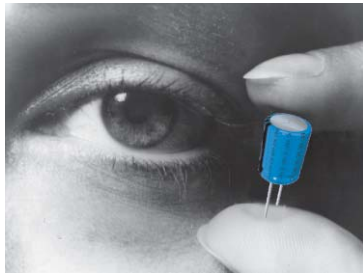
E-96 Series



4 digit marking for E96  
ex. 1542:  $154 \times 10^2 = 15K4\Omega$

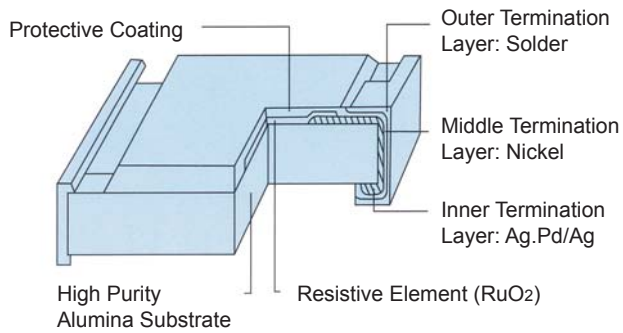


3 digit marking for E96 - 0603  
ex. 0C2 (see table)  
 $102 \times 10^2 = 10K2\Omega$

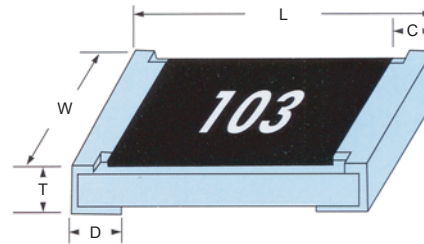


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△ Configuration



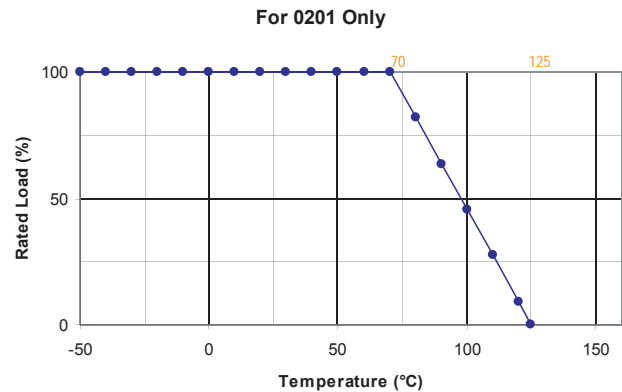
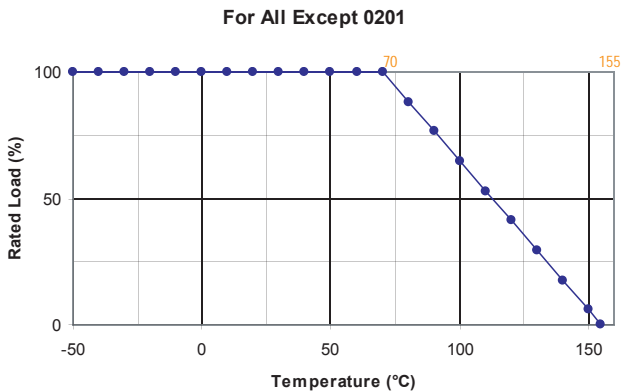
△ Dimensions



Size	L	W	C	D	T
0201	0.60 ± 0.05	0.30 ± 0.05	0.25 ± 0.05	0.15 ± 0.05	0.25 ± 0.05
0402	1.00 ± 0.05	0.50 ± 0.05	0.20 ± 0.10	0.25 ± 0.10	0.35 ± 0.05
0603	1.60 ± 0.10	0.80 ± 0.10	0.30 ± 0.20	0.30 ± 0.20	0.45 ± 0.10
0805	2.00 ± 0.15	1.20 ± 0.15	0.40 ± 0.20	0.40 ± 0.20	0.50 ± 0.10
1206	3.10 ± 0.15	1.60 ± 0.15	0.50 ± 0.25	0.50 ± 0.25	0.55 ± 0.10
1210	3.10 ± 0.15	2.65 ± 0.15	0.50 ± 0.20	0.50 ± 0.25	0.55 ± 0.10
2010	5.00 ± 0.20	2.50 ± 0.20	0.60 ± 0.25	0.60 ± 0.25	0.60 ± 0.10
2512	6.30 ± 0.20	3.10 ± 0.20	0.60 ± 0.25	0.60 ± 0.25	0.60 ± 0.15
1225	3.10 ± 0.20	6.30 ± 0.20	0.60 ± 0.25	0.90 ± 0.25	0.60 ± 0.15

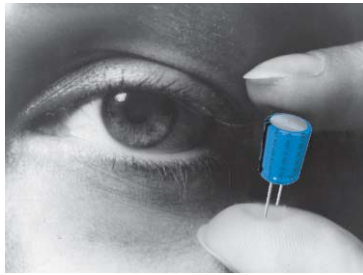
units: mm

△ Power Derating Curve



\*Maximum dissipation in percentage of rated power as a function of the ambient temperature.

Surface Mount Resistors



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Δ Rating

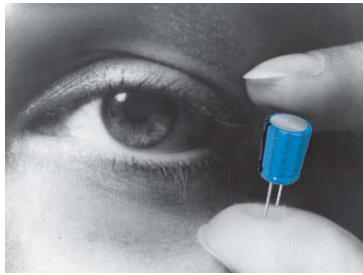
Type	Size	Power Rating at 70 °C	Max. RCWV	Max. Overload Voltage	Resistance Tolerance (%)	Temperature Coefficient (TCR; ppm/ °C)	Resistance Range		Standard Resistance Values
							Min.	Max.	
0201	1/20W	15V	30V	± 1%(F)	± 300	10Ω	1M Ω	E-24	
				± 5%(J)		0Ω & 1Ω	1M Ω		
0402	1/16W	50V	100V	± 1%(F)	± 200	10Ω	1M Ω	E-96	
				± 5%(J)		0Ω & 1Ω	10M Ω	E-24	
0603	1/10W	50V	100V	±0.1%(B)	± 50	20Ω	510K Ω	E-96	
				±0.25%(C)	± 50	20Ω	510K Ω	E-96	
0805	1/8W	150V	300V	± 0.5%(D)	± 50	20Ω	510K Ω	E-96	
				± 1%(F)	± 100 ± 50	10Ω	1M Ω	E-96	
1206	1/4W	200V	400V	± 2%(G)	± 200	1Ω	10M Ω	E-24	
				± 5%(J)	± 200	0Ω & 1Ω	10M Ω	E-24	
2010	1/2W	200V	400V	± 1%(F)	± 100	1Ω	10M Ω	E-96	
				± 5%(J)	± 200	0Ω & 1Ω	10M Ω	E-24	
2512	1W	200V	400V	± 1%(F)	± 100	1Ω	10M Ω	E-96	
				± 5%(J)	± 200	0Ω & 1Ω	10M Ω	E-24	

- Jumper : ● 0201,0402,0603 size maximum resistance  $R_{max} \leq 50m \Omega$  and rated current  $I_R \leq 1A$   
 ● 0805,1206,2010,2512 size maximum resistance  $R_{max} \leq 50m \Omega$  and rated current  $I_R \leq 2A$   
 1Ω ~10 Ω : ● Temperature Coefficient of Resistance for 0402,0603,0805,1206 = -300~+500  
 ● Temperature Coefficient of Resistance for 0201,2010,2512 = ± 300

Δ Low Resistance

Type	Size	Power Rating at 70 °C	Max. RCWV	Max. Overload Voltage	Resistance Tolerance (%)	Temperature Coefficient (TCR; ppm/ °C)	Resistance Range	
							Min.	Max.
0603	1/10W	302mV	754mV	± 1%(F)	± 300	100m Ω	910m Ω	
0805	1/8W	337mV	843mV	± 5%(J)	± 400	50m Ω	91m Ω	
1206	1/4W	477mV	1192mV		± 200	50m Ω	910m Ω	
2010	1/2W	675mV	1686mV	± 1%(F)	± 400	40m Ω	47m Ω	
				± 5%(J)	± 600	22m Ω	39m Ω	
2512	1W	954mV	2385mV		± 1000	10m Ω	20m Ω	
1225	2W	1349mV	3373mV	± 1%(F)	± 100	20m Ω	910m Ω	
				± 5%(J)	± 150	10m Ω	19m Ω	

Surface Mount Resistors



Thick Film Chip Resistors  
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△ Specifications and Test Methods

ITEM	SPECIFICATION	TEST METHOD
DC Resistance	J: ± 5%    G: ± 2%    F: ± 1% D: ± 0.5%    C: ± 0.25%    B: ± 0.1% Zero ohm Jumper < 50mΩ	IEC 60115-1 4.5 / JIS C 5202 5.1 Measure the resistance value.
Short time Overload	J,G: Δ R ≤ ± (2% + 0.1 Ω) F,D: Δ R ≤ ± (1% + 0.05 Ω) C,B: Δ R ≤ ± (0.5% + 0.05 Ω)	IEC 60115-1 4.13 / JIS C 5202 5.5 2.5X Rated voltage or Max. Overload Voltage for 5 sec. measure resistance after 30 minutes
Solderability	Over 95% of termination must be covered with solder	IEC 60115-1 4.17 / JIS C 5202 6.5 After immersing flux, dip in the 245 ± 2°C molten solder bath for 3 ± 0.5 sec.
Resistance to Solder Heat	J,G: Δ R ≤ ± (1% + 0.1 Ω) F,D,C,B: Δ R ≤ ± (0.5% + 0.05 Ω) No mechanical damage	IEC 60115-1 4.18 / JIS C 5202 6.4 With 260 ± 5°C for 10 ± 1 sec.
Temperature Coefficient of Resistance (TCR)	J,G: ± 200ppm/°C F: ± 100 ± 50ppm/°C D,C,B: ± 50ppm/°C	IEC 60115-1 4.8.4.2 / JIS C 5202 5.2 Test temperature : 25 °C(T1) → -55°C(T2) 25°C(T1) → 125°C(T2)  $TCR (ppm/°C) = \frac{R2-R1}{R1} \times \frac{1}{T2-T1} \times 10^6$ T1: 25°C T2: Test temperature R1: Resistance at reference temperature (T1) R2: Resistance at test temperature (T2)
Load Life Humidity	J,G: Δ R ≤ ± (3% + 0.1 Ω) F,D: Δ R ≤ ± (1% + 0.05 Ω) C,B: Δ R ≤ ± (0.5% + 0.05 Ω)	IEC 60115-1 4.24.2 / JIS C 5202 7.9 Maintain the temperature of the resistor at 40 ± 2°C and 90~95% R.H. with the rated voltage applied. Cycle ON for 1.5 hours and OFF for 0.5 hour for 1000+48/-0 hours. After 1~4 hour, measure the resistance value.
Load Life	J,G: Δ R ≤ ± (3% + 0.1 Ω) F,D: Δ R ≤ ± (1% + 0.05 Ω) C,B: Δ R ≤ ± (0.5% + 0.05 Ω)	IEC 60115-1 4.25.1 / JIS C 5202 7.10 Permanent resistance change after 1000+48/-0 hours (1.5 hours ON, 0.5 hour OFF) at RCWV or Max. Keep the resistor at 70 ± 2°C ambient
Intermittent Overload	Δ R ≤ ± (5% + 0.1 Ω) No mechanical damage	JIS C 5202 5.8 4.0xRated voltage (Max. Overload Voltage) 1 sec ON, 25 sec OFF, test 10,000 cycles
Temperature Cycle	J,G: Δ R ≤ ± (1% + 0.1 Ω) F,D,C,B: Δ R ≤ ± (0.5% + 0.05 Ω) No mechanical damage	IEC 60115-1 4.19 / JIS C 5202 7.4 Repeat 5 cycles as follows -55°C(30 min.) ~ + 25 °C(2~3 min.) +125°C(30 min.) ~ + 25 °C(2~3 min.) for 0201 -55°C(30 min.) ~ + 25 °C(2~3 min.) +155°C(30 min.) ~ + 25 °C(2~3 min.) for others
Insulation Resistance	Between termination and coating must be over 1000M Ω	IEC 60115-1 4.6.1.1 / JIS C 5202 5.6 Test voltage: 100 ± 15V
Bending Strength	J,G: Δ R ≤ ± (1% + 0.1 Ω) F,D,C,B: Δ R ≤ ± (0.5% + 0.05 Ω) No mechanical damage	IEC 60115-1 4.33 Resistance change after bended on the 90mm PCB. Bend: 3mm for 0201, 0402, 0603, 0805 2mm for 1206, 2010, 1225, 2512

Surface Mount Resistors



Thick Film Chip Resistors  
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△ Specifications and Test Methods

ITEM	SPECIFICATION	TEST METHOD
DC Resistance	J: ± 5%, F: ±1%	IEC 60115-1 4.5 / JIS C 5202 5.1 Measure the resistance value.
Short time Overload	J: Δ R ≤ ± (2% + 0.5m Ω) F: Δ R ≤ ± (1% + 0.5m Ω)	IEC 60115-1 4.13 / JIS C 5202 5.5 2.5X Rated voltage or Max. Overload Voltage for 5 sec. measure resistance after 30 minutes
Solderability	Over 95% of termination must be covered with solder	IEC 60115-1 4.17 / JIS C 5202 6.5 After immersing flux, dip in the 245 ± 2 °C molten solder bath for 3 ± 0.5 sec.
Resistance to Solder Heat	J: Δ R ≤ ± (1% + 0.5m Ω) F: Δ R ≤ ± (0.5% + 0.5m Ω) No mechanical damage	IEC 60115-1 4.18 / JIS C 5202 6.4 With 260 ± 5 °C for 10 ± 1 sec.
Temperature Coefficient of Resistance (TCR)	Size : 0603 , 0805 100mΩ ~ 910mΩ : ± 300ppm/°C Size : 1206 , 2010 , 2512 50mΩ ~ 910mΩ : ± 200ppm/°C Size : 1225 20mΩ ~ 910mΩ : ± 100ppm/°C reference for other resistance range in page 4	IEC 60115-1 4.8.4.2 / JIS C 5202 5.2 Test temperature : 25 °C(T1) → -55°C(T2) 25°C(T1) → -125°C(T2) $TCR (ppm/°C) = \frac{R2-R1}{R1} \times \frac{1}{T2-T1} \times 10^6$ T1: 25°C T2: Test temperature R1: Resistance at reference temperature (T1) R2: Resistance at test temperature (T2)
Load Life Humidity	J: Δ R ≤ ± (3% + 0.5m Ω) F: Δ R ≤ ± (1% + 0.5m Ω)	IEC 60115-1 4.24.2 / JIS C 5202 7.9 Maintain the temperature of the resistor at 40 ± 2 °C and 90~95% R.H. with the rated voltage applied. Cycle ON for 1.5 hours and OFF for 0.5 hour for 1000+48/-0 hours. After 1~4 hour, measure the resistance value.
Load Life	J: Δ R ≤ ± (3% + 0.5m Ω) F: Δ R ≤ ± (1% + 0.5m Ω)	IEC 60115-1 4.25.1 / JIS C 5202 7.10 Permanent resistance change after 1000+48/-0 hours (1.5 hours ON , 0.5 hour OFF) at RCWV or Max. Keep the resistor at 70 ± 2 °C ambient
Temperature Cycle	J: Δ R ≤ ± (1% + 1m Ω) F: Δ R ≤ ± (0.5% + 1m Ω) No mechanical damage	IEC 60115-1 4.19 / JIS C 5202 7.4 Repeat 5 cycles as follows -55°C(30 min.) ~ +25 °C(2~3 min.) +125°C(30 min.) ~ +25 °C(2~3 min.) for 0201 -55°C(30 min.) ~ +25 °C(2~3 min.) +155°C(30 min.) ~ +25 °C(2~3 min.) for others
Insulation Resistance	Between termination and coating must be over 1000M Ω	IEC 60115-1 4.6.1.1 / JIS C 5202 5.6 Test voltage: 100 ± 15V
Bending Strength	J: Δ R ≤ ± (1% + 1m Ω) F: Δ R ≤ ± (0.5% + 1m Ω) No mechanical damage	IEC 60115-1 4.33 Resistance change after bended on the 90mm PCB. Bend: 3mm for 0201 , 0402 , 0603 , 0805 2mm for 1206 , 2010 , 1225 , 2512